

WHAT IS CLAIMED IS:

1. A printed circuit board comprising:

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a circuit pattern formed on a surface of a base substrate of which surface is at least composed of an insulative material;

an insulative layer formed over the surface of said base substrate including said circuit pattern and composed of a mixed insulative material of more than two kinds of organic resins having a different etching rate by a dry etching process;

a hole for connection perforated on said insulative layer by a laser beam or like;

a conductive film for electroplating process as a foundation of electroplating formed on the surface of said insulative layer by a vacuum film forming process after roughing the surface of said insulative layer by removing a part of the surface of said insulative layer with a dry etching process; and

a conductive layer formed over said conductive film by an electroplating process,

wherein said conductive layer is connected with said circuit pattern electrically.

2. A manufacturing method of a printed circuit board comprising steps of:

forming a circuit pattern on a surface of a base substrate of which surface is at least composed of an insulative material;

forming an insulative layer over the surface of said base substrate including said circuit pattern and said insulative layer composed of a mixed insulative material of more than two kinds of

organic resins having a different etching rate by a dry etching process;

perforating a hole for connection on said insulative layer by a laser beam or like;

roughing the surface of said insulative layer by removing a part of the surface of said insulative layer with a dry etching process;

forming a conductive film for electroplating process as a foundation of electroplating on the surface of said insulative layer by a vacuum film forming process; and

forming a conductive layer over said conductive film by an electroplating process,

wherein said conductive layer is connected with said circuit pattern electrically.

3. The manufacturing method of a printed circuit board in accordance with claim 2, wherein said dry etching process is an ion bombard method by inert gas such as Ar (argon).

4. The manufacturing method of a printed circuit board in accordance with claim 2, wherein a degree of roughness in said step of roughing the surface of said insulative layer is from 0.1 to 2 μm .